

CMIMX7 *Computer-on-Module*

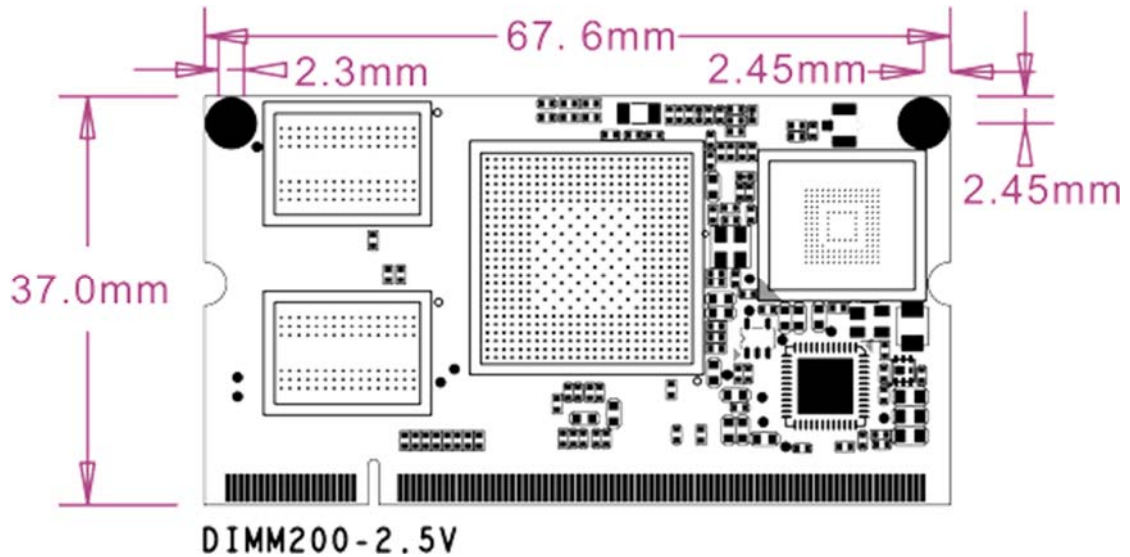
Interface Connection





1 PCB Dimension

Figure 1. PCB Dimension



2 Interface Connection

The baseboard uses a 200 pin SODIMM card edge interface for CPU board interfacing.

2.1 SODIMM200 Card Edge Socket Specifications

Figure 2. SODIMM Socket (2.5V, H=5.2mm, on the baseboard)





SPECIFICATIONS

Mechanical

Contact Retention Force: 0.10kg min.
Durability : 25 Cycles

Electrical

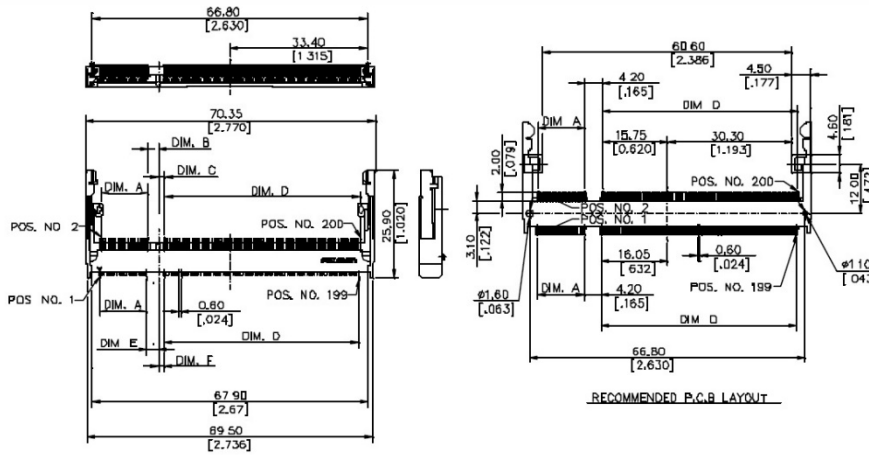
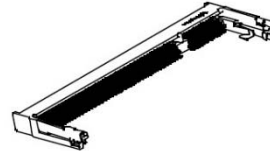
Voltage Rating: 25V
Current Rating: 0.3A
Contact Resistance: 50mΩ max.
Dielectric Withstanding Voltage: 250V AC/1 min.
Insulation Resistance: 100MΩ

Physical

Housing: Thermoplastic, UL 94V-0 rated in Ivory Color
Contact: Copper alloy
Plating: See "ORDERING INFORMATION"
Metal Spring: Copper alloy
Operating Temperature: -40°C to +85°C

DDR II SO DIMM Socket

AS Series
5.2mm Height SMT Type
0.60mm [.024"] Pitch
200 Pos.



ORDERING INFORMATION

PRODUCT NO.: A S 0 A4 2 6 - N 2 * N * F

Memory Module Socket — A
Horizontal Type — S
Single Row — 0
No. of Pos. — A4
A4=200 Pos.
SMT Type — 2
Contact Area Plating — 6=10µ Gold

F=Lead Free
1=Hard Tray
4=Soft Tray
7=Tape Reel
N=Normal Type
S=Standard Type
R=Reverse Type
2=5.2mm Height
N=DDR II SO DIMM (Type II)

ASDA426-N2RN-4F	11.40 [.449]	1.80 [.071]	2.40 [.094]
ASOA426-N2SN-1F	47.40 [1.866]	2.70 [.106]	1.50 [.059]
P/N	DIM. D	DIM. E	DIM. F
ASDA426-N2RN-4F	47.40 [1.866]	1.50 [.059]	2.70 [.106]
ASOA426-N2SN-1F	11.40 [.449]	2.40 [.094]	1.80 [.071]
P/N	DIM. A	DIM. B	DIM. C